

In the Specification:

Please replace the Description Of The Drawings beginning on page 2, line 29, with the following:

Description Of The Drawings

Fig. 1 is a schematic diagram of a system by which ordering and manufacturing is performed;

Fig. 1A is a schematic diagram of a system including process steps for the performance of ordering and manufacturing;

Figure 2 is a side view of a tangible device in the form of a polishing pad[.];

Figure 3 is a top view of the pad disclosed by Figure 2;

Figure 4 is a magnified view of a cross-section of a groove;

Figure 5 is a cross section of a polishing carrier;

Figure 6 is a top view of a tangible device in the form of a wafer carrier;

Figure 7 is a diagram of a system for handling an order, scheduling manufacturing and controlling manufacturing process commands; and

Figure 8 is a diagram of a system for computer control of a device production unit.

Please replace the paragraph beginning on page 11, line 17, with the following paragraph:

The hardness and stiffness of the upper layer (14) is adjusted to suit the requirements of the polishing operation for which it is employed, by varying the type of polymer used, varying the porosity, and by incorporating material in other phases or states, such as, liquid, solid, ionic, molecular or crystalline phases or states. The invention is suitable for manufacturing a tangible device from a polymer that includes, but is not limited to, acrylates, polyurethanes, polystyrenes, polyesters, polysulfones, nylons, epoxies, natural and synthetic rubbers, and copolymers of two or more polymer species. These polymers are of various classes, including, but not limited to, aqueous latexes, solution polymers (i.e., polymers dissolved in a solvent that polymerize as the solvent evaporates), mix and set polymers, thermoplastic polymers, thermoset polymers, or photo-cured polymers. Each type

and class of polymer has particular advantages for manufacture of a tangible device with selected attributes including, size, shape, porosity, texture, hardness, hydrofilicity, hydrophilicity, hydrophobicity, other properties of materials and materials phase selection.